

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSP88 H6327	**Issued**	03. April 2021
MA#	MA001626786		
Package	PG-SOT223-4-21	**Weight***	113.48 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.007	0.01		59	
	noble metal	gold	7440-57-5	0.026	0.02		228	
	inorganic material	silicon	7440-21-3	0.294	0.26	0.29	2590	2877
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		447	
	non noble metal	chromium	7440-47-3	0.152	0.13		1340	
	non noble metal	copper	7440-50-8	50.489	44.49	44.67	444909	446785
wire	non noble metal	copper	7440-50-8	0.019	0.02	0.02	165	165
encapsulation	organic material	carbon black	1333-86-4	0.605	0.53		5328	
	plastics	epoxy resin	-	9.069	7.99		79913	
	inorganic material	silicondioxide	60676-86-0	50.785	44.76	53.28	447510	532751
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12901	12901
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4521	4521
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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